



UC-160 UV LEDs



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Features:

- Supply wide UV-A wavelength from 365nm to 430nm
- Over 5W/cm2 of Optical power typical from 390nm to 430nm
- High thermal conductivity package:
- > Junction to heat sink thermal resistance of < 0.3℃/W
- High radiometric efficiency
- Environmentally friendly: RoHS compliant, mercury-free
- Variable drive currents: less than 4.5A through 6A
- Easy use for Linear UV light source



Applications:

- Curing:
- > Inks > Coatings > Adhesives
- Inspection
- Machine Vision
- Fiber-coupled illumination
- Specialty Projection Systems for Maskless Lithography
- Rapid Prototyping and 3D printing
- Medical and Scientific Instrumentation



Technology of Overviews

FLEDA COB Multi-chips LED package benefit from innovations in device technology, chip package and thermal management. This suite of technologies give engineers and system designers the freedom to develop solutions both high in power and efficiency.

FLEDA Technology

FLEDA's technology enables to emit large area photons uniformly over the entire COB UV LED surface. The intense optical power density produced by these multi-chips facilitate designs which replace mercury lamps where arrays of traditional power LEDs cannot.

For UV devices, FLEDA's side-less structure to let the engineers easy to design the linear UV LED light source and instead of the linear mercury lamps with power density 80W/cm -120W/cm.

Packaging Technology

Thermal management is critical in high power LED applications. FLEDA UC-160 UV LEDs have the lowest thermal resistance of any LED on the market with a thermal resistance from junction to heat sink of 0.3℃/W or 0.35℃/W. This allows the LED to be driven at higher current densities while maintaining a low junction temperature, thereby resulting in brighter solutions and longer lifetimes.

Reliability Technology

Designed from the ground up, FLEDA COB Multi-chips LEDs are one of the most reliable light sources in the world today. COB Multi-chips LEDs have passed a rigorous suite of environmental and mechanical stress tests, including mechanical shock, vibration, temperature cycling and humidity, and high current applications. With very low failure rates and median lifetimes that typically exceed 10,000 hours, FLEDA COB Multi-chips LEDs are ready for evern the most demanding applications.

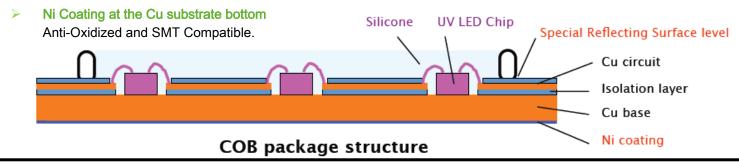
Environmental Benefits

FLEDA LEDs help reduce power consumption and the amount of hazardous waste entering the environment. All COB Multi-chips LED products manufactured by FLEDA are RoHS compliant and free fo hazardous materials, including lead and mercury.

The Advantages of COB Multi-chips LEDs

Every FLEDA LED is fully designed to ensure that it meets the high quality standards expected from FLEDA's products.

- Low Thermal Resistance <0.16°C/W / High thermal conductivity 401W/(m.K)</p>
 Copper Substrate and LED Chip Direct Bonding on Cu Base
- Special Reflecting Surface
 No Ag Plating, Anti-Sulfide, and Low Light Decay.





Optical & Electric Characteristics

Optical Characteristics (Ta=25°C)

Parameter	Symbol	Wavelength	Conditions	Min.	Тур.	Max.	Unit
Irradiance Note[1]	Ee	365-370 nm	- IF=6000mA	0.25	0.5	-	- W/cm2
		370-380 nm		0.5	0.75	-	
		380-390 nm		3	3.4	-	
		390-410 nm		4	5.5	-	
View Angle	2⊝ _{1/2}	X-Axis	- IF=6000mA	140	150	160	Degree
		Y-Axis		120	130	140	

Note: [1] Irradiance measured by DYMAX ACCU-CAL 50-LED Meter, and the distance of test is 5 mm.

Electric Characteristics (Ta=25°C)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF=6000mA	26	-	30	V
Reverse Current Note[1]	lr	VR=5V			10	uA
Thermal Resistance	RthJ-B	IF=6000mA		0.1		°C/W
Junction to Board	K(IIJ-D					
Temperature Coefficient fo	A\/ /AT	IF=6000mA	-	-64	-	mV/°C
Forward Voltage	$\Delta V_F/\Delta T$					

Note: [1] Singe chip VR

Absolute Maximum Rating (Ta=25°C)

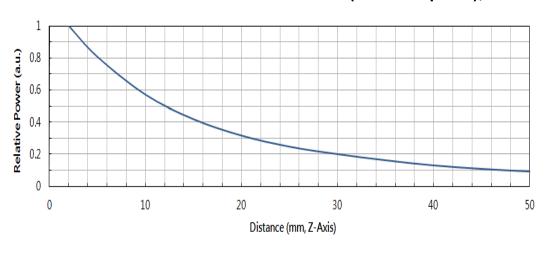
Parameter	Symbol	Ratings	Unit	
Power Dissipation	PD	200	W	
Continuous Forward Current	IF	7000	mA	
Peak Forward Current Note[1]	IF(Peak)	10,000	mA	
LED Junction Temperature	Tj	120	$^{\circ}\!\mathbb{C}$	
Operating Temperature Range	Topr	30°C To +80°C		
Storage Temperature Range	Tstg	-40°C To +100°C		
Manual Soldering Temperature	Tsol	260°C±20°C For 3-5 Seconds		
ESD Sensitivity Note[2]	ESD	500V HBM		

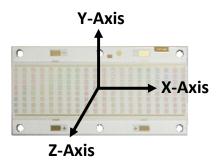
Note: [1] Condition for IFP is pulse of 10% duty cycle @ 1kHz

[2]Singe chip ESD

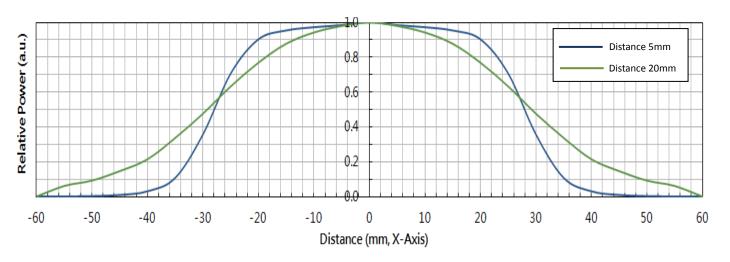
Optical & Electric Characteristics

Relative Power vs Distance (at central point), I_F=6000mA

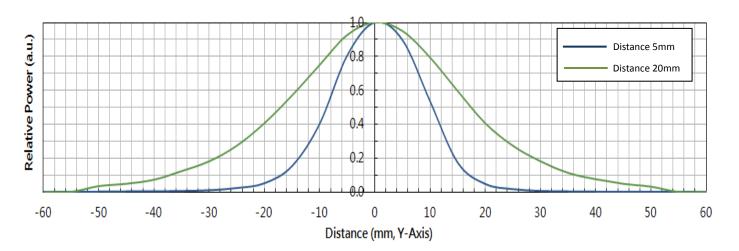




Relative Power vs X-Axis, I_F=6000mA



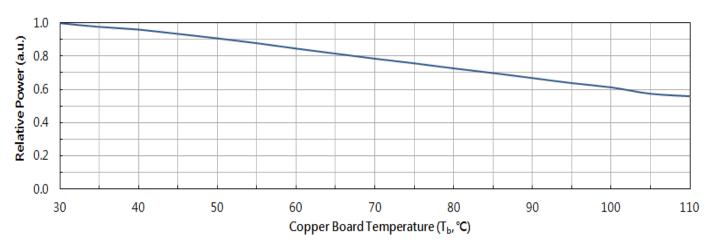
Relative Power vs Y-Axis, I_F=6000mA



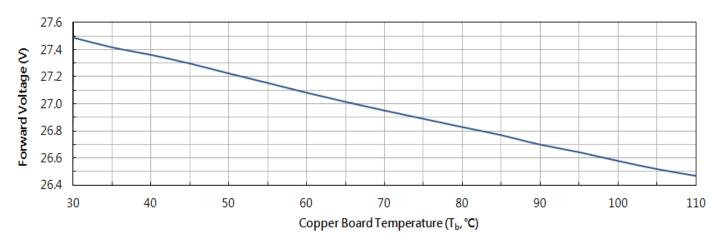


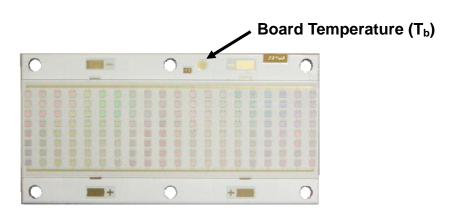
Optical & Electric Characteristics

Relative Power vs Board Temperature (T_b)



Forward Voltage vs Board Temperature (T_b)

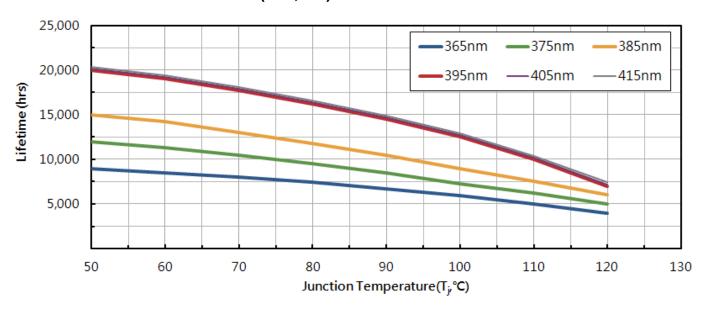




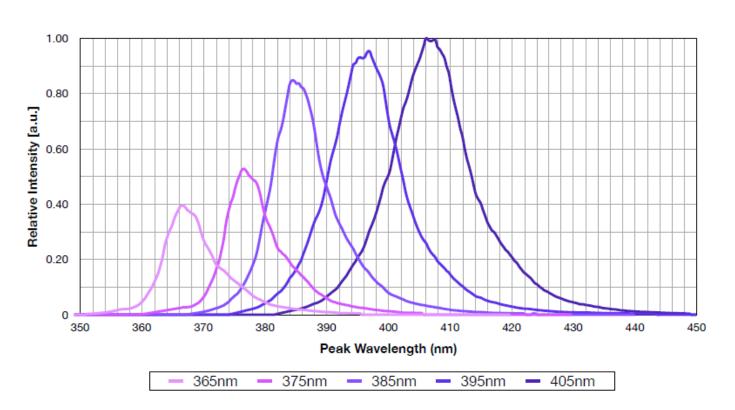


UV COB LED Reliability

UC-160 (B50,L70) Lifetimes @ IF=6000mA



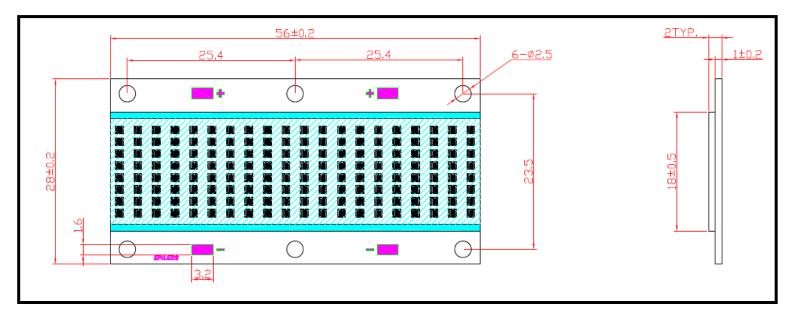
UV COB LED Spectrum Distribution





Mechanical Dimensions

Dimensions in millimeters



LED Array: 8s20p Typical Voltage: 28V

Operating Current: 6000mA

Notes:

(1) All dimensions are in millimeters.

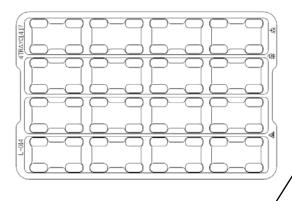
(2) Tolerance is ±0.25mm



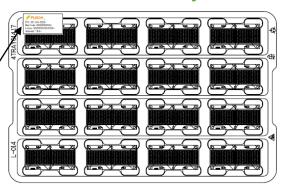


Packing Informations - UC-160

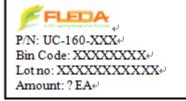
PET Tray Dimension



Put Emitter onto tray



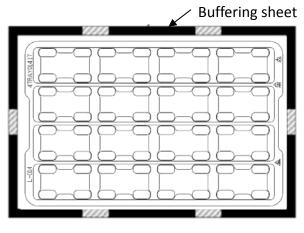
Label format



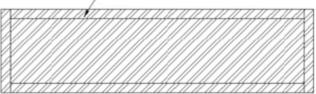
Stack 15 tray with 1 cover (full) Add bubble sheet if not full



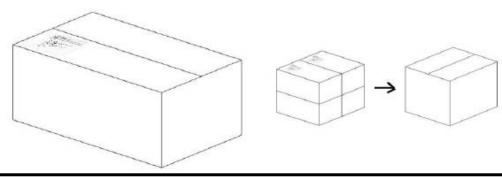
Put tray into Buffering sheet



Buffering sheet cover



Put into Carton and add label outside Put into Outer Box (4 cartons)



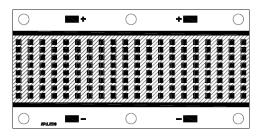


Notice

Assembly Notice

(1) Do not touch emitting area.

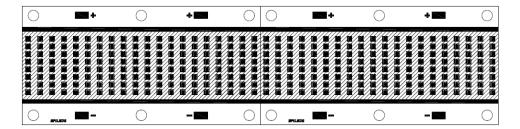
Do not touch or scratch silicon forming matrix area since it could damage the bonding of LED chips or wires and cause dead zone.



Don't touch the surface of Emitter

(2) Assembly guideline

Wiring emitter's anode/cathode pad, then fix emitter with screws onto heat sink.



(3) Soldering methods

- a) Set up the temperature of welding head to 400±10° when soldering.
- b) Put Emitter on a 100±10°C hot plate and set up welding head temperature to 300±10°C
- c) Either is OK.

(4) Wires

Suggested using strand wires (softer) to connect power, don't use solid wires.

Used Notice

- (1) In order to avoid absorption of moisture, it is recommended that the products are sotred in the dry box (or desiccators) with a desiccants. Alternatively the following environment is recommended. Storage temperature: 5°C ~ 30°C , Humidity: 60% HR Max.
- (2) Soldering rapidly cooling should be avoided.
- (3) Products should not be assembly on distorted surface of heat sink.
- (4) Products should not contact with any types of fluid, such as water, oil, organic solvents,...etc.
- (5) The maximum ambient temperature should be taken into consideration when determining the operating current.
- (6) This product must be driven by constant power supplier.



- (7) ESD Precautions Static Electricity and surge damages LEDs. It is recommended that wrist bands or anti-electrostatic gloves be used when handing the LEDs. All devices, equipment, and machinery should be properly grounded.
- (8) The appearance and specifications of product may be modified for improvement without notice.

Ordering Information

Color	Order Code		eak ngth (nm)	Light Intensity (W/cm²)		
		Min	Max	Min	Max	
UV	UC-160-415	410	420	4	6	
	UC-160-405	400	410	4	6	
	UC-160-395	390	400	4	6	
	UC-160-385	380	390	3	4	
	UC-160-375	370	380	0.5	0.75	
	UC-160-365	365	370	0.25	0.5	



DISCLAIMER

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